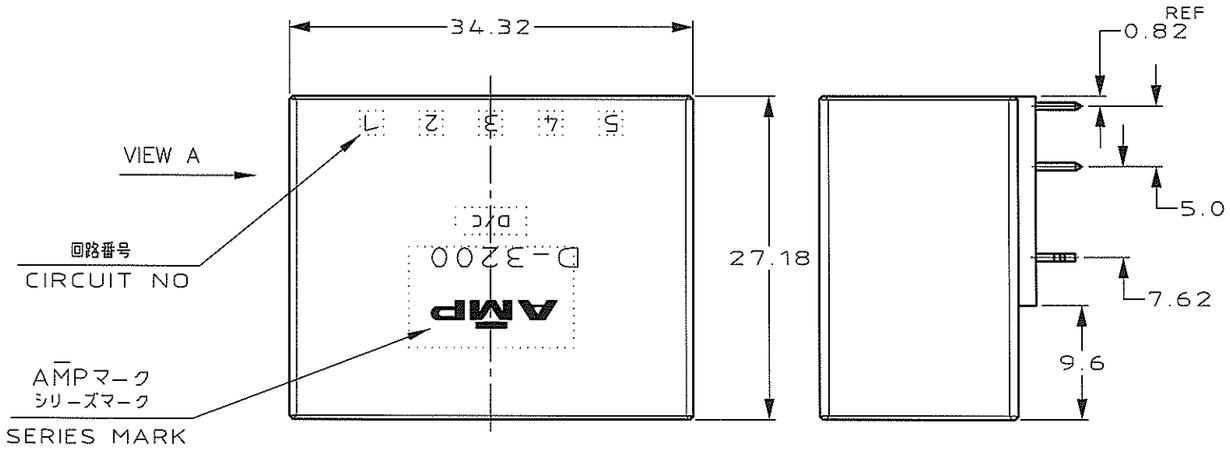

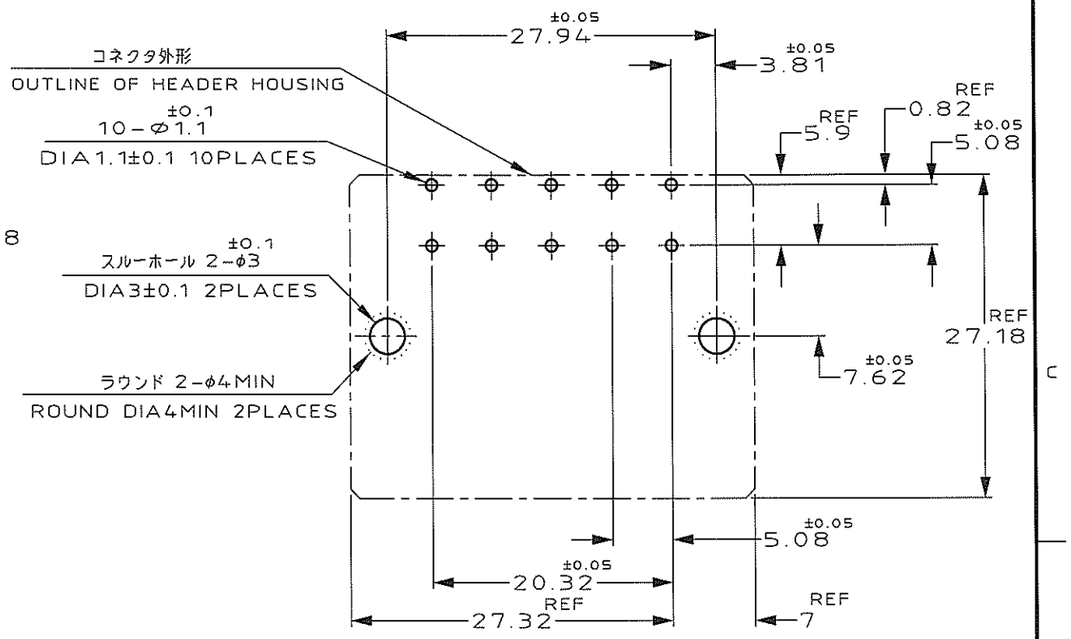

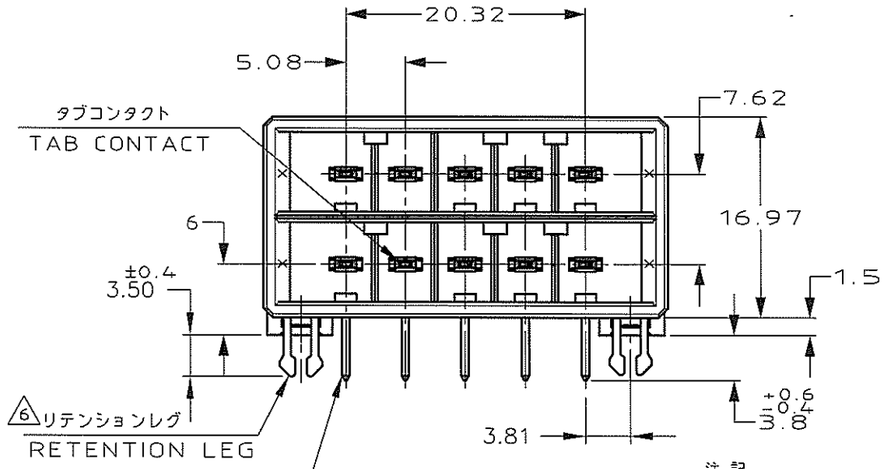

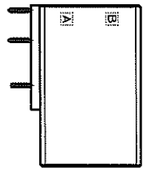

VIEW A
(SCALE:1:1)

推奨基板取付け穴寸法
PC 基板厚:1.6±0.1
(非累積公差)
(コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN
PC BOARD THICKNESS:1.6±0.1
(NOT ACCUMULATE TOLERANCE)
(CONNECTOR MOUNT SIDE)

注記
1. 材料: ハウジング: ガラス入り熱可塑性
ポリエステル樹脂 (94V-0),色: 黒
コンタクト: 銅合金
リテンションレグ: 銅合金
2. めっき: コンタクト: 全面Ni下地
接触部:0.38μm MIN金めっき
3. めっき: コンタクト: 全面Ni下地
接触部:0.76μm MIN金めっき
4. めっき: コンタクト: 全面Ni下地
接触部:2.0 μm MINスズめっき
~~5. めっき: リテンションレグとコンタクト半田付部~~
~~: ニッケル下地の上に半田めっき~~
6. めっき: リテンションレグとコンタクト半田付部 : ニッケル下地の上にスズめっき

NOTES
1. MATERIAL:HOUSING:GLASS FILED THERMO PLASTIC,POLYESTER(94V-0),COLOR:BLACK
CONTACT:COPPER ALLOY
RETENTION LEG:COPPER ALLOY
2. FINISH(CONTACT AREA):0.38 mMIN GOLD PLATING OVER Ni PLATING
3. FINISH(CONTACT AREA):0.76 mMIN GOLD PLATING OVER Ni PLATING
4. FINISH(CONTACT AREA):2.0 PLATED OVER NICKEL
~~5. FINISH(RETENTION LEG): TIN LEAD PLATED (CONTACT TAIL)~~
6. FINISH(RETENTION LEG): TIN PLATED (CONTACT TAIL)

	KEYING LOCATION	A ROW KEYING	B ROW KEYING	FINISH	製品番号 PART NO.
B ROW / A ROW		X	Y	6 4	3-316080-5
				6 3	3-316080-3
				6 2	3-316080-2
B ROW / A ROW		Y	Y	6 4	2-316080-5
				6 3	2-316080-3
				6 2	2-316080-2
B ROW / A ROW		X	X	6 4	1-316080-5
				6 3	1-316080-3
				6 2	1-316080-2

TE Connectivity

B3	REVISED PER ECO-11-005030	RK	HMR	25MAR11
LTR	REVISION RECORD	DR	CHK	DATE

WIRE RANGE mm²(AWG -)	INSULATION DIA - mmφ
MATERIAL SEE NOTE 注記参照	FINISH SEE NOTE 注記参照
DR. 4/JUL/'95 K.IKEDA	DE. 4/JUL/'95 K.IKEDA
CHK.	APP.

NAME
10 POS DOUBLE ROW
HORIZONTAL HDR ASS'Y FOR DYNAMIC D-3200

一般公差 (GENERAL TOLERANCE)
10以下 : ±0.3
10を超え 30以下 : ±0.4
30を超え100以下 : ±0.45
角度 : ±3°

SIZE	LOC	NUMBER
A3	J	C-316080

SCALE	REV.	SHEET
2-1	B3	1 OF 1

(CUSTOMER DRAWING) 顧客用図面

METRIC
NUMBER 316080
3rd ANGLE PROJECTION
DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT
PRINT DIST